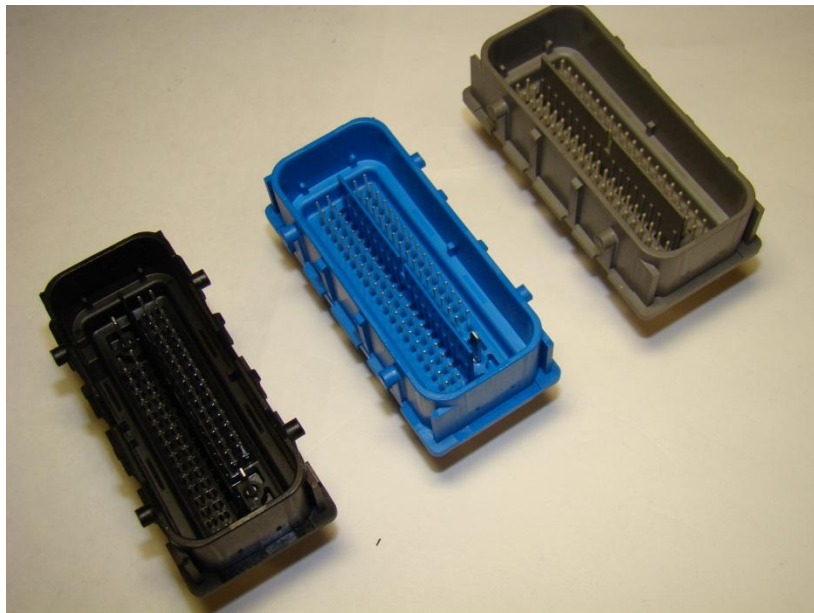


1.0 SCOPE: This manual contains supplemental information pertaining to the Molex MX123 Header product line; Molex series numbers 31386 (small footprint) and 31387 (large footprint)

2.0 PRODUCT DESCRIPTION: The MX123 Header product line is a series of headers with the following pin configurations: 56 circuits, 66 circuits, 73 circuits, and 80 circuits. It features through hole solder pins for the PCB interface and either gold or silver plating for the connector interface. It is designed to mate with the Molex MX123 connector family, series numbers 34566 and 34576, see reference document list for applicable specifications.



Large footprint headers assemblies



Small footprint header assembly

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3.0 REFERENCE DOCUMENTS:

Product Drawings

- SD-31386-056 – 56 Circuit Header, small footprint
- SD-31387-066 – 66 Circuit Header, large footprint
- SD-31387-073 – 73 Circuit Header, large footprint
- SD-31387-080 – 80 Circuit Header, large footprint

Product Specifications

- PS-31386-200 – Small footprint
- PS-31387-200 – Large footprint

Packaging Specifications

- PK-31300-840 – Gold plated terminals
- PK-31300-916 – Silver plated terminals

Mating interface (Reference information only)

- SD-31387-173 – Large footprint
- SD-31386-156 – Small footprint

Connector Interface

- SD-34566-001 – 66 / 73 / 80 Circuit configurations
- SD-34576-001 – 56 Circuit configurations
- AS-34566-001 – MX123 Connector Application Specification

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AS-31386-200	Tim Skiver	Dante Dunn	Dave Krawczyk

4.0 PROCEDURE

4.1 ASSEMBLY INSTRUCTIONS:

- Please ensure that care is taken to avoid damaging the terminals or the plastic during the assembly process
- Powder free nitrile disposable gloves should be worn when handling the header assemblies
- Assembly shall not exceed 125°C during post processing or during the attachment process

4.2 HEADER TO MATING INTERFACE ASSEMBLY

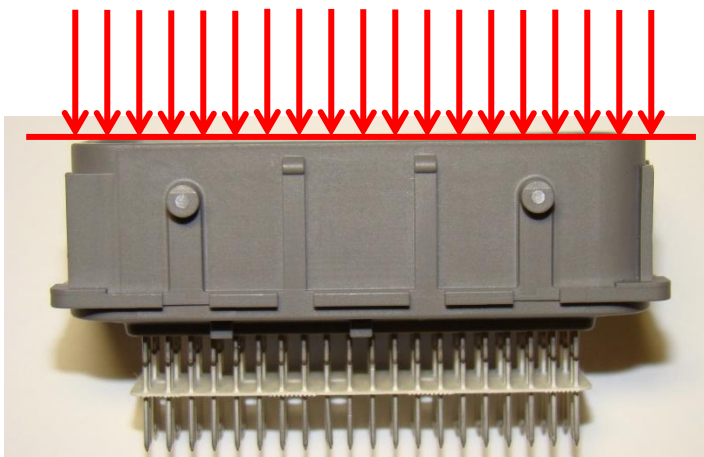
- Adhesive for the attachment: As a general guideline, Molex uses silicone based adhesives as an attachment method to create a permanent adhesive bond between the shroud and the mating component.

- Touch Locations:



The part should be handled from the sides, avoiding contact with any of the pins

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TEMPLATE FILENAME: APPLICATION_SPEC[SIZE_A](V.1).DOC			



Pressure should be applied evenly across the top surface ('A' Datum) of the part when attaching to the mating interface.

REVISION INFORMATION:

REVISION	DATE	DESCRIPTION
A	1/31/13	Initial Release

NOTE: PLEASE REFER TO MOLEX.COM TO ENSURE THE LATEST REVISION OF THIS DOCUMENT

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